

Design of a Two-Phase Loop Thermosyphon for Telecommunications System (II) — Analysis and Simulation —

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A computer simulation is performed for a two-phase loop thermosyphon for the B-ISDN telecommunications. The aim of this code development is to provide capabilities to predict the affects of many variables on the performance of the proposed TLT system using different empirical correlations obtained from the literature for the evaporation and condensation, and the shape factors available. In the present study, the simulation code is based on the sectorial thermal resistance network built on the flow regimes of the two-phase flows involved. The nodal resistances are solved by the typical Gauss-Seidal iteration method. The code can predict whether the proposed design is possible based on the flooding limit calculation of the system and its results are compared with the experimental results.

Key Words: Thermosyphon, Sectorial Thermal Resistance, Simulation, Two-Phase Flow, Shape Factor

Nomenclature

A	: Area (m^2)	G	: Mass flux (kg/m^2s)
A_f	: Flow area occupied by liquid phase (m^2)	g	: Acceleration due to gravity (m^2/s)
A_g	: Flow area occupied by vapour phase (m^2)	H	: Specific enthalpy (J/kg)
a	: Evaporator thickness (m)	h	: Heat transfer coefficient (W/m^2K), evaporator depth (m)
A_x	: Cross sectional area (m^2)	H_{fluid}	: Specific enthalpy of fluid (J/kg)
b	: Evaporator width (m)	H_f	: Specific enthalpy of saturated liquid (J/kg)
C	: Parameter	H_{fg}	: Latent heat of evaporation (J/kg)
C_{pl}	: Specific heat of saturated liquid ($J/kg K$)	k	: Thermal conductivity ($W/m K$)
C_{SF}	: A constant on Rohsenow's pool boiling correlation	L	: Length (m)
D	: Outer diameter of tube (m), parameter	Nu	: Nusselt number
d	: Inner diameter (m)	ΔP_a	: Acceleration pressure drop
D_h	: Hydraulic diameter (m)	ΔP_f	: Frictional pressure drop
F	: Frictional parameter	ΔP_h	: Hydraulic pressure drop
f	: Friction factor	P	: Pressure (Pa)
		$(dP/dy)_p$: Pressure gradient
		Pr	: Prandtl number
		Q	: Heat transfer rate (W)
		q	: Heat flux (W/cm^2)
		R	: Resistance (K/W)
		r	: Radius (m)
		Ra	: Rayleigh number
		Re	: Reynolds number
		S	: Shape factor, defined as eqn. (2)

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